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Indium Corporation Experts Address Power Electronics and Thermal Management Solutions at PCIM Expo 2026

CLINTON, N.Y., May 26, 2026 — Indium Corporation®, a leading provider of high-reliability soldering, sintering, and thermal interface materials for power electronics devices, will feature three experts addressing critical industry challenges at PCIM Expo 2026, June 9-11, in Nuremberg, Germany.

Tuesday, June 9
2:35 p.m. CEST (e-Mobility Stage) – *Improving Thermomechanical Reliability of Power Modules with Aluminum-Graphite Baseplates and Advanced Solder Preforms* presented by Ryan Mayberry, Senior Applications Development Engineer, Engineered Solder Materials (ESM). Co-Presenter: Klaus Hoell, Team Leader, Thermal Management & Innovation, Schunk Carbon Technology GmbH.

- This presentation examines Aluminum-Graphite and advanced solder preform technologies, including Indalloy®276 InFORMS®, for power module applications. Evaluating assembly considerations and thermal shock reliability against industry standards will reveal performance advantages that support next-generation packaging designs as power densities increase and reliability demands grow across evolving power electronics systems.

Wednesday, June 10
2:10 p.m. CEST (e-Mobility Stage) – *Materials Technologies Enabling the Next-Generation of Power Distribution for AI Data Center Infrastructure* presented by Andreas Karch, Regional Technical Manager and Technologist – Advanced Applications. Co-Presenter: Syeda Qurat ul ain Akbar, Senior Staff Product Applications Engineer, Infineon Technologies AG.

- This presentation addresses challenges in the field of energy management, now also driven by AI and high-performance computing. It evaluates state-of-the-art and emerging materials for power device interconnects and thermal management, highlighting their role in supporting efficiency and reliability. The talk includes a case study on device-to-heat-sink soldering, demonstrating improved thermal performance in advanced data center power distribution systems.

Thursday, June 11
2:20 p.m. CEST (Seoul, Level 1) – *Innovative Approach for Transient Liquid Phase Soldering (TLPS) with Solder Preforms for Power Module Packaging* presented by Ryan Mayberry, Senior Applications Development Engineer, ESM.

- This technical conference presentation evaluates Transient Liquid Phase Soldering (TLPS) materials technology and its application in power devices, with specific focus on die-attach and substrate-attach interfaces. An ultra-thin, pure-metal interface approach is demonstrated to achieve strong mechanical bonds at dissimilar interfaces while minimizing thermal resistance through reduced bondline thickness. Practical assembly and processing methods are also explored, providing further evidence that TLPS is a compelling alternative to conventional methods as power electronics demand increasingly robust and thermally efficient materials solutions.

Thursday, June 11
3:50 p.m. CEST (Exhibitor Stage) – *Next Generation Soldering Technology for EV Inverter Package-Cooler Attach* presented by Joe Hertline, Senior Product Manager – ESM/Power Electronics.

- This session explores material selection at the package-cooler interface for EV inverters, emphasizing total cost of ownership, highlighting soldering as a cost-effective attach method while addressing process trade-offs. It introduces a novel solder alloy technology that can reduce process temperatures, offer robust wettability to maximize the process window, and balance reliability and thermal performance to achieve cost-of-ownership objectives.

To learn more about Indium Corporation's next-generation solder technologies, visit indium.com or meet with our experts at PCIM Expo 2026, Hall 6, Booth 358.

About Indium Corporation
Indium Corporation® is a premier materials refiner, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit http://www.indium.com/ or email jhuang@indium.com. You can also follow our experts, From One Engineer To Another® (#FOETA), at www.linkedin.com/company/indium-corporation/.

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